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Details

Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	I ² C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	91
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12a256vpve

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Section 1 IntroductionMC9S12DT256

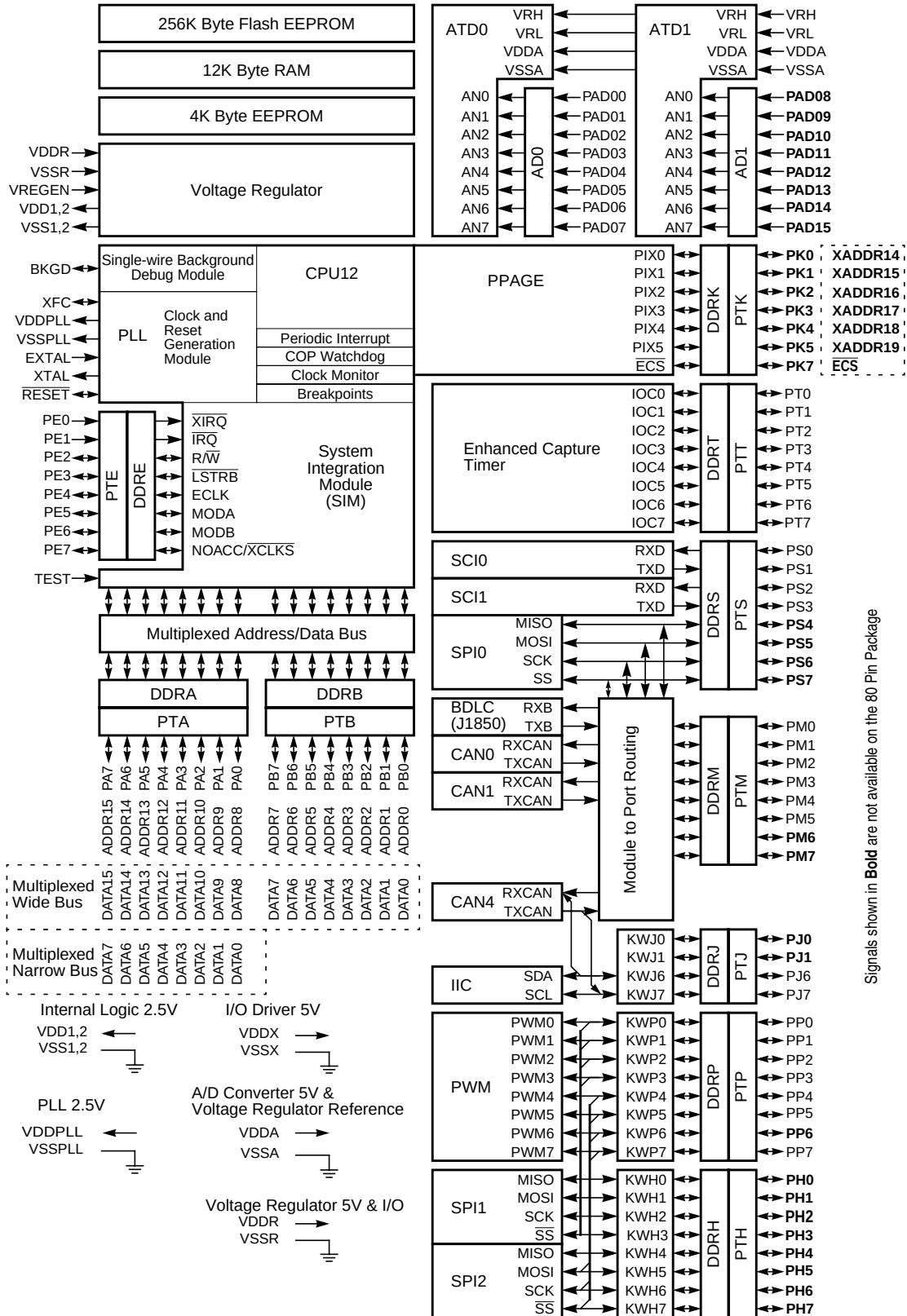
1.1 Overview

The MC9S12DT256 microcontroller unit (MCU) is a 16-bit device composed of standard on-chip peripherals including a 16-bit central processing unit (HCS12 CPU), 256K bytes of Flash EEPROM, 12K bytes of RAM, 4K bytes of EEPROM, two asynchronous serial communications interfaces (SCI), three serial peripheral interfaces (SPI), an 8-channel IC/OC enhanced capture timer, two 8-channel, 10-bit analog-to-digital converters (ADC), an 8-channel pulse-width modulator (PWM), a digital Byte Data Link Controller (BDLC), 29 discrete digital I/O channels (Port A, Port B, Port K and Port E), 20 discrete digital I/O lines with interrupt and wakeup capability, three CAN 2.0 A, B software compatible modules (MSCAN12), and an Inter-IC Bus. The MC9S12DT256 has full 16-bit data paths throughout. However, the external bus can operate in an 8-bit narrow mode so single 8-bit wide memory can be interfaced for lower cost systems. The inclusion of a PLL circuit allows power consumption and performance to be adjusted to suit operational requirements.

1.2 Features

- HCS12 Core
 - 16-bit HCS12 CPU
 - i. Upward compatible with M68HC11 instruction set
 - ii. Interrupt stacking and programmer's model identical to M68HC11
 - iii. Instruction queue
 - iv. Enhanced indexed addressing
 - MEBI (Multiplexed External Bus Interface)
 - MMC (Module Mapping Control)
 - INT (Interrupt control)
 - BKP (Breakpoints)
 - BDM (Background Debug Mode)
- CRG
 - Low current Colpitts or Pierce oscillator
 - PLL
 - COP watchdog
 - Real time interrupt
 - Clock Monitor
- 8-bit and 4-bit ports with interrupt functionality
 - Digital filtering

Figure 1-1 MC9S12DT256 Block Diagram



1.5 Device Memory Map

Table 1-1 and **Figure 1-2** show the device memory map of the MC9S12DT256 after reset. Note that after reset the bottom 1k of the EEPROM (\$0000 - \$03FF) are hidden by the register space.

Table 1-1 Device Memory Map

Address	Module	Size (Bytes)
\$0000 - \$0017	CORE (Ports A, B, E, Modes, Inits, Test)	24
\$0018 - \$0019	Reserved	2
\$001A - \$001B	Device ID register (PARTID)	2
\$001C - \$001F	CORE (MEMSIZ, IRQ, HPRI0)	4
\$0020 - \$0027	Reserved	8
\$0028 - \$002F	CORE (Background Debug Mode)	8
\$0030 - \$0033	CORE (PPAGE, Port K)	4
\$0034 - \$003F	Clock and Reset Generator (PLL, RTI, COP)	12
\$0040 - \$007F	Enhanced Capture Timer 16-bit 8 channels	64
\$0080 - \$009F	Analog to Digital Converter 10-bit 8 channels (ATD0)	32
\$00A0 - \$00C7	Pulse Width Modulator 8-bit 8 channels (PWM)	40
\$00C8 - \$00CF	Serial Communications Interface (SCI0)	8
\$00D0 - \$00D7	Serial Communications Interface (SCI1)	8
\$00D8 - \$00DF	Serial Peripheral Interface (SPI0)	8
\$00E0 - \$00E7	Inter IC Bus	8
\$00E8 - \$00EF	Byte Data Link Controller (BDLC)	8
\$00F0 - \$00F7	Serial Peripheral Interface (SPI1)	8
\$00F8 - \$00FF	Serial Peripheral Interface (SPI2)	8
\$0100 - \$010F	Flash Control Register	16
\$0110 - \$011B	EEPROM Control Register	12
\$011C - \$011F	Reserved	4
\$0120 - \$013F	Analog to Digital Converter 10-bit 8 channels (ATD1)	32
\$0140 - \$017F	Motorola Scalable Can (CAN0)	64
\$0180 - \$01BF	Motorola Scalable Can (CAN1)	64
\$01C0 - \$01FF	Reserved	64
\$0200 - \$023F	Reserved	64
\$0240 - \$027F	Port Integration Module (PIM)	64
\$0280 - \$02BF	Motorola Scalable Can (CAN4)	64
\$02C0 - \$03FF	Reserved	320
\$0000 - \$0FFF	EEPROM array	4096

\$0010 - \$0014**MMC map 1 of 4 (Core User Guide)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0012	INITEE	Read:	EE15	EE14	EE13	EE12	EE11	0	0	EEON
		Write:								
\$0013	MISC	Read:	0	0	0	0	EXSTR1	EXSTR0	ROMHM	ROMON
		Write:								
\$0014	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0015 - \$0016**INT map 1 of 2 (Core User Guide)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0015	ITCR	Read:	0	0	0	WRINT	ADR3	ADR2	ADR1	ADR0
		Write:								
\$0016	ITEST	Read:	INTE	INTC	INTA	INT8	INT6	INT4	INT2	INT0
		Write:								

\$0017 - \$0017**MMC map 2 of 4 (Core User Guide)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0017	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

\$0018 - \$001B**Miscellaneous Peripherals (Device User Guide, Table 1-3)**

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$0018	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$0019	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
\$001A	PARTIDH	Read:	ID15	ID14	ID13	ID12	ID11	ID10	ID9	ID8
		Write:								
\$001B	PARTIDL	Read:	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
		Write:								

\$001C - \$001D**MMC map 3 of 4 (Core and Device User Guide, Table 1-4)**

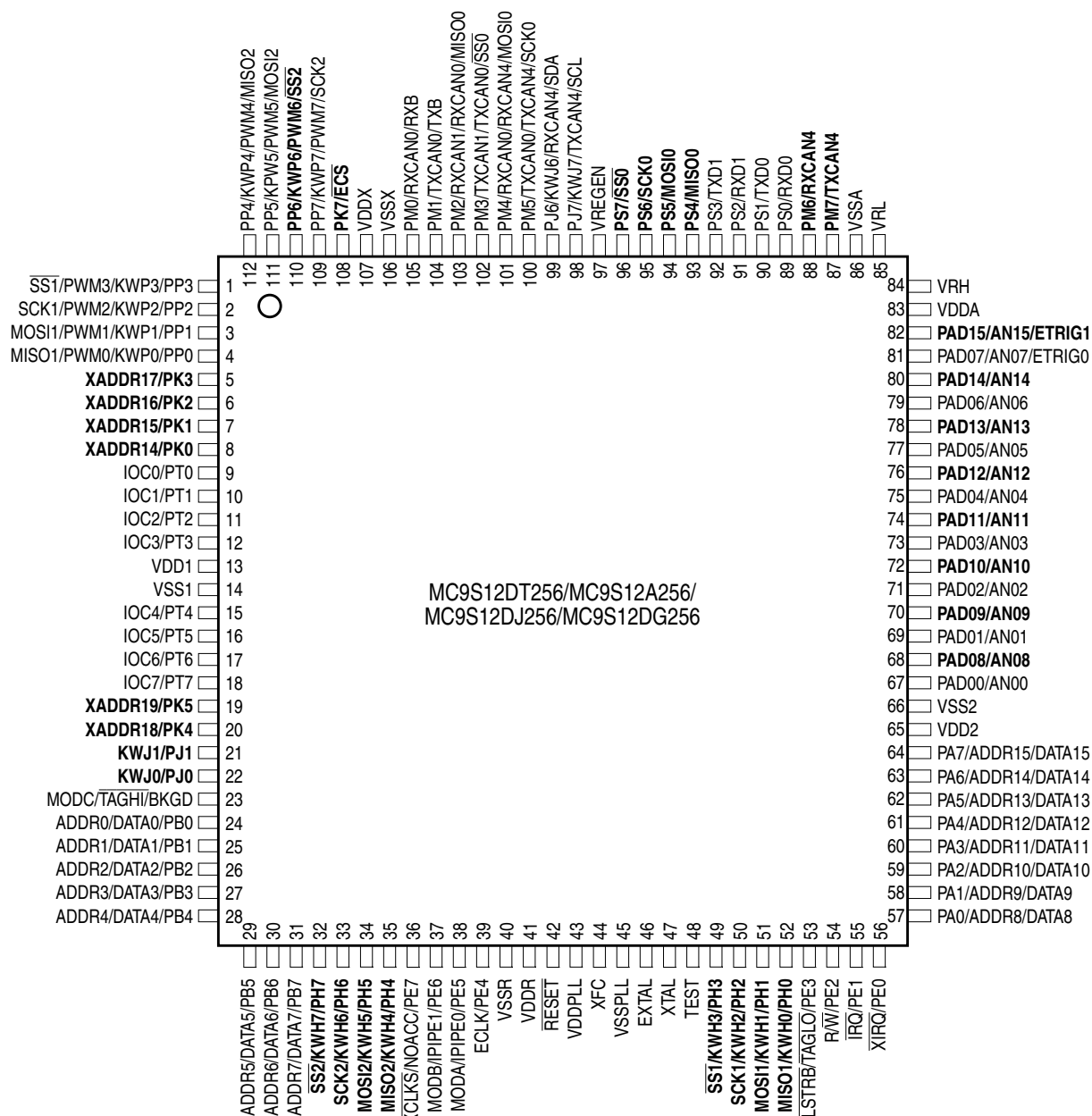
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
\$001C	MEMSIZ0	Read:	reg_sw0	0	eep_sw1	eep_sw0	0	ram_sw2	ram_sw1	ram_sw0
		Write:								
\$001D	MEMSIZ1	Read:	rom_sw1	rom_sw0	0	0	0	0	pag_sw1	pag_sw0
		Write:								

Section 2 Signal Description

This section describes signals that connect off-chip. It includes a pinout diagram, a table of signal properties, and detailed discussion of signals. It is built from the signal description sections of the Block User Guides of the individual IP blocks on the device.

2.1 Device Pinout

The MC9S12DT256/MC9S12DJ256/MC9S12DG256 and MC9S12A256 is available in a 112-pin low profile quad flat pack (LQFP) and MC9S12DJ256/MC9S12DG256 and MC9S12A256 is also available in a 80-pin quad flat pack (QFP). Most pins perform two or more functions, as described in the Signal Descriptions. **Figure 2-1** and **Figure 2-2** show the pin assignments.



Signals shown in **Bold** are not available on the 80 Pin Package

Figure 2-1 Pin Assignments in 112-pin LQFP

2.3.40 PM1 / TXCAN0 / TXB — Port M I/O Pin 1

PM1 is a general purpose input or output pin. It can be configured as the transmit pin TXCAN of the Motorola Scalable Controller Area Network controller 0 (CAN0). It can be configured as the transmit pin TXB of the BDLC.

2.3.41 PM0 / RXCAN0 / RXB — Port M I/O Pin 0

PM0 is a general purpose input or output pin. It can be configured as the receive pin RXCAN of the Motorola Scalable Controller Area Network controller 0 (CAN0). It can be configured as the receive pin RXB of the BDLC.

2.3.42 PP7 / KWP7 / PWM7 / SCK2 — Port P I/O Pin 7

PP7 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 7 output. It can be configured as serial clock pin SCK of the Serial Peripheral Interface 2 (SPI2).

2.3.43 PP6 / KWP6 / PWM6 / $\overline{SS}2$ — Port P I/O Pin 6

PP6 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 6 output. It can be configured as slave select pin $\overline{SS}$ of the Serial Peripheral Interface 2 (SPI2).

2.3.44 PP5 / KWP5 / PWM5 / MOSI2 — Port P I/O Pin 5

PP5 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 5 output. It can be configured as master output (during master mode) or slave input pin (during slave mode) MOSI of the Serial Peripheral Interface 2 (SPI2).

2.3.45 PP4 / KWP4 / PWM4 / MISO2 — Port P I/O Pin 4

PP4 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 4 output. It can be configured as master input (during master mode) or slave output (during slave mode) pin MISO of the Serial Peripheral Interface 2 (SPI2).

2.3.46 PP3 / KWP3 / PWM3 / $\overline{SS}1$ — Port P I/O Pin 3

PP3 is a general purpose input or output pin. It can be configured to generate an interrupt causing the MCU to exit STOP or WAIT mode. It can be configured as Pulse Width Modulator (PWM) channel 3 output. It can be configured as slave select pin $\overline{SS}$ of the Serial Peripheral Interface 1 (SPI1).

Mnemonic	Pin Number	Nominal Voltage	Description
	112-pin QFP		
V _{DDPLL}	43	2.5 V	Provides operating voltage and ground for the Phased-Locked Loop. This allows the supply voltage to the PLL to be bypassed independently. Internal power and ground generated by internal regulator.
V _{SSPLL}	45	0 V	
VREGEN	97	5V	Internal Voltage Regulator enable/disable

2.4.7 VREGEN — On Chip Voltage Regulator Enable

Enables the internal 5V to 2.5V voltage regulator. If this pin is tied low, VDD1,2 and VDDPLL must be supplied externally.

Table 4-2 Clock Selection Based on PE7

PE7 = XCLKS	Description
0	Pierce Oscillator/external clock selected

Table 4-3 Voltage Regulator VREGEN

VREGEN	Description
1	Internal Voltage Regulator enabled
0	Internal Voltage Regulator disabled, VDD1,2 and VDDPLL must be supplied externally with 2.5V

4.3 Security

The device will make available a security feature preventing the unauthorized read and write of the memory contents. This feature allows:

- Protection of the contents of FLASH,
- Protection of the contents of EEPROM,
- Operation in single-chip mode,
- Operation from external memory with internal FLASH and EEPROM disabled.

The user must be reminded that part of the security must lie with the user's code. An extreme example would be user's code that dumps the contents of the internal program. This code would defeat the purpose of security. At the same time the user may also wish to put a back door in the user's program. An example of this is the user downloads a key through the SCI which allows access to a programming routine that updates parameters stored in EEPROM.

4.3.1 Securing the Microcontroller

Once the user has programmed the FLASH and EEPROM (if desired), the part can be secured by programming the security bits located in the FLASH module. These non-volatile bits will keep the part secured through resetting the part and through powering down the part.

The security byte resides in a portion of the Flash array.

Check the Flash Block User Guide for more details on the security configuration.

4.3.2 Operation of the Secured Microcontroller

4.3.2.1 Normal Single Chip Mode

This will be the most common usage of the secured part. Everything will appear the same as if the part was not secured with the exception of BDM operation. The BDM operation will be blocked.

4.3.2.2 Executing from External Memory

The user may wish to execute from external space with a secured microcontroller. This is accomplished by resetting directly into expanded mode. The internal FLASH and EEPROM will be disabled. BDM operations will be blocked.

4.3.3 Unsecuring the Microcontroller

In order to unsecure the microcontroller, the internal FLASH and EEPROM must be erased. This can be done through an external program in expanded mode.

Once the user has erased the FLASH and EEPROM, the part can be reset into special single chip mode. This invokes a program that verifies the erasure of the internal FLASH and EEPROM. Once this program completes, the user can erase and program the FLASH security bits to the unsecured state. This is generally done through the BDM, but the user could also change to expanded mode (by writing the mode bits through the BDM) and jumping to an external program (again through BDM commands). Note that if the part goes through a reset before the security bits are reprogrammed to the unsecure state, the part will be secured again.

4.4 Low Power Modes

The microcontroller features three main low power modes. Consult the respective Block User Guide for information on the module behavior in Stop, Pseudo Stop, and Wait Mode. An important source of information about the clock system is the Clock and Reset Generator User Guide (CRG).

4.4.1 Stop

Executing the CPU STOP instruction stops all clocks and the oscillator thus putting the chip in fully static mode. Wake up from this mode can be done via reset or external interrupts.

4.4.2 Pseudo Stop

This mode is entered by executing the CPU STOP instruction. In this mode the oscillator is still running and the Real Time Interrupt (RTI) or Watchdog (COP) sub module can stay active. Other peripherals are turned off. This mode consumes more current than the full STOP mode, but the wake up time from this mode is significantly shorter.

4.4.3 Wait

This mode is entered by executing the CPU WAI instruction. In this mode the CPU will not execute instructions. The internal CPU signals (address and databus) will be fully static. All peripherals stay active. For further power consumption the peripherals can individually turn off their local clocks.

Section 5 Resets and Interrupts

5.1 Overview

Consult the Exception Processing section of the HCS12 Core User Guide for information on resets and interrupts.

5.2 Vectors

5.2.1 Vector Table

Table 5-1 lists interrupt sources and vectors in default order of priority.

Table 5-1 Interrupt Vector Locations

Vector Address	Interrupt Source	CCR Mask	Local Enable	HPRIO Value to Elevate
\$FFFE, \$FFFF	Reset	None	None	—
\$FFFC, \$FFFD	Clock Monitor fail reset	None	PLLCTL (CME, SCME)	—
\$FFFA, \$FFFB	COP failure reset	None	COP rate select	—
\$FFF8, \$FFF9	Unimplemented instruction trap	None	None	—
\$FFF6, \$FFF7	SWI	None	None	—
\$FFF4, \$FFF5	XIRQ	X-Bit	None	—
\$FFF2, \$FFF3	IRQ	I-Bit	IRQCR (IRQEN)	\$F2
\$FFF0, \$FFF1	Real Time Interrupt	I-Bit	CRGINT (RTIE)	\$F0
\$FFEE, \$FFEF	Enhanced Capture Timer channel 0	I-Bit	TIE (C0I)	\$EE
\$FFEC, \$FFED	Enhanced Capture Timer channel 1	I-Bit	TIE (C1I)	\$EC
\$FFEA, \$FFEB	Enhanced Capture Timer channel 2	I-Bit	TIE (C2I)	\$EA
\$FFE8, \$FFE9	Enhanced Capture Timer channel 3	I-Bit	TIE (C3I)	\$E8
\$FFE6, \$FFE7	Enhanced Capture Timer channel 4	I-Bit	TIE (C4I)	\$E6
\$FFE4, \$FFE5	Enhanced Capture Timer channel 5	I-Bit	TIE (C5I)	\$E4
\$FFE2, \$FFE3	Enhanced Capture Timer channel 6	I-Bit	TIE (C6I)	\$E2
\$FFE0, \$FFE1	Enhanced Capture Timer channel 7	I-Bit	TIE (C7I)	\$E0
\$FFDE, \$FFDF	Enhanced Capture Timer overflow	I-Bit	TSRC2 (TOF)	\$DE
\$FFDC, \$FFDD	Pulse accumulator A overflow	I-Bit	PACTL (PAOVI)	\$DC
\$FFDA, \$FFDB	Pulse accumulator input edge	I-Bit	PACTL (PAI)	\$DA
\$FFD8, \$FFD9	SPI0	I-Bit	SP0CR1 (SPIE, SPTIE)	\$D8
\$FFD6, \$FFD7	SCI0	I-Bit	SC0CR2 (TIE, TCIE, RIE, ILIE)	\$D6
\$FFD4, \$FFD5	SCI1	I-Bit	SC1CR2 (TIE, TCIE, RIE, ILIE)	\$D4
\$FFD2, \$FFD3	ATD0	I-Bit	ATD0CTL2 (ASCIE)	\$D2

\$FFD0, \$FFD1	ATD1	I-Bit	ATD1CTL2 (ASCIE)	\$D0
\$FFCE, \$FFCF	Port J	I-Bit	PTJIF (PTJIE)	\$CE
\$FFCC, \$FFCD	Port H	I-Bit	PTHIF(PTHIE)	\$CC
\$FFCA, \$FFCB	Modulus Down Counter underflow	I-Bit	MCCTL(MCZI)	\$CA
\$FFC8, \$FFC9	Pulse Accumulator B Overflow	I-Bit	PBCTL(PBOVI)	\$C8
\$FFC6, \$FFC7	CRG PLL lock	I-Bit	CRGINT(LOCKIE)	\$C6
\$FFC4, \$FFC5	CRG Self Clock Mode	I-Bit	CRGINT (SCMIE)	\$C4
\$FFC2, \$FFC3	BDLC	I-Bit	DLCBCR1(IE)	\$C2
\$FFC0, \$FFC1	IIC Bus	I-Bit	IBCR (IBIE)	\$C0
\$FFBE, \$FFBF	SPI1	I-Bit	SP1CR1 (SPIE, SPTIE)	\$BE
\$FFBC, \$FFBD	SPI2	I-Bit	SP2CR1 (SPIE, SPTIE)	\$BC
\$FFBA, \$FFBB	EEPROM	I-Bit	ECNFG (CCIE, CBEIE)	\$BA
\$FFB8, \$FFB9	FLASH	I-Bit	FCNFG (CCIE, CBEIE)	\$B8
\$FFB6, \$FFB7	CAN0 wake-up	I-Bit	CAN0RIER (WUPIE)	\$B6
\$FFB4, \$FFB5	CAN0 errors	I-Bit	CAN0RIER (CSCIE, OVRIE)	\$B4
\$FFB2, \$FFB3	CAN0 receive	I-Bit	CAN0RIER (RXFIE)	\$B2
\$FFB0, \$FFB1	CAN0 transmit	I-Bit	CAN0TIER (TXEIE2-TXEIE0)	\$B0
\$FFAE, \$FFAF	CAN1 wake-up	I-Bit	CAN1RIER (WUPIE)	\$AE
\$FFAC, \$FFAD	CAN1 errors	I-Bit	CAN1RIER (CSCIE, OVRIE)	\$AC
\$FFAA, \$FFAB	CAN1 receive	I-Bit	CAN1RIER (RXFIE)	\$AA
\$FFA8, \$FFA9	CAN1 transmit	I-Bit	CAN1TIER (TXEIE2-TXEIE0)	\$A8
\$FFA6, \$FFA7	Reserved			
\$FFA4, \$FFA5				
\$FFA2, \$FFA3				
\$FFA0, \$FFA1				
\$FF9E, \$FF9F				
\$FF9C, \$FF9D				
\$FF9A, \$FF9B				
\$FF98, \$FF99				
\$FF96, \$FF97	CAN4 wake-up	I-Bit	CAN4RIER (WUPIE)	\$96
\$FF94, \$FF95	CAN4 errors	I-Bit	CAN4RIER (CSCIE, OVRIE)	\$94
\$FF92, \$FF93	CAN4 receive	I-Bit	CAN4RIER (RXFIE)	\$92
\$FF90, \$FF91	CAN4 transmit	I-Bit	CAN4TIER (TXEIE2-TXEIE0)	\$90
\$FF8E, \$FF8F	Port P Interrupt	I-Bit	PTPIF (PTPIE)	\$8E
\$FF8C, \$FF8D	PWM Emergency Shutdown	I-Bit	PWMSDN (PWMIE)	\$8C
\$FF80 to \$FF8B	Reserved			

The VDDX, VSSX, VDDR and VSSR pairs supply the I/O pins, VDDR supplies also the internal voltage regulator.

VDD1, VSS1, VDD2 and VSS2 are the supply pins for the digital logic, VDDPLL, VSSPLL supply the oscillator and the PLL.

VSS1 and VSS2 are internally connected by metal.

VDDA, VDDX, VDDR as well as VSSA, VSSX, VSSR are connected by anti-parallel diodes for ESD protection.

NOTE: *In the following context VDD5 is used for either VDDA, VDDR and VDDX; VSS5 is used for either VSSA, VSSR and VSSX unless otherwise noted. IDD5 denotes the sum of the currents flowing into the VDDA, VDDX and VDDR pins. VDD is used for VDD1, VDD2 and VDDPLL, VSS is used for VSS1, VSS2 and VSSPLL. IDD is used for the sum of the currents flowing into VDD1 and VDD2.*

A.1.3 Pins

There are four groups of functional pins.

A.1.3.1 5V I/O pins

Those I/O pins have a nominal level of 5V. This class of pins is comprised of all port I/O pins, the analog inputs, BKGD and the RESET pins. The internal structure of all those pins is identical, however some of the functionality may be disabled. E.g. for the analog inputs the output drivers, pull-up and pull-down resistors are disabled permanently.

A.1.3.2 Analog Reference

This group is made up by the VRH and VRL pins.

A.1.3.3 Oscillator

The pins XFC, EXTAL, XTAL dedicated to the oscillator have a nominal 2.5V level. They are supplied by VDDPLL.

A.1.3.4 TEST

This pin is used for production testing only.

A.1.3.5 VREGEN

This pin is used to enable the on chip voltage regulator.

A.1.7 Operating Conditions

This chapter describes the operating conditions of the device. Unless otherwise noted those conditions apply to all the following data.

NOTE: Please refer to the temperature rating of the device (C, V, M) with regards to the ambient temperature T_A and the junction temperature T_J . For power dissipation calculations refer to **Section A.1.8 Power Dissipation and Thermal Characteristics**.

Table A-4 Operating Conditions

Rating	Symbol	Min	Typ	Max	Unit
I/O, Regulator and Analog Supply Voltage	V_{DD5}	4.5	5	5.25	V
Digital Logic Supply Voltage ¹	V_{DD}	2.35	2.5	2.75	V
PLL Supply Voltage ¹	V_{DDPLL}	2.35	2.5	2.75	V
Voltage Difference VDDX to VDDR and VDDA	ΔV_{DDX}	-0.1	0	0.1	V
Voltage Difference VSSX to VSSR and VSSA	ΔV_{SSX}	-0.1	0	0.1	V
Oscillator	f_{osc}	0.5	-	16	MHz
Bus Frequency	f_{bus}	0.5	-	25	MHz
MC9S12DT256C					
Operating Junction Temperature Range	T_J	-40	-	100	°C
Operating Ambient Temperature Range ²	T_A	-40	27	85	°C
MC9S12DT256V					
Operating Junction Temperature Range	T_J	-40	-	120	°C
Operating Ambient Temperature Range ²	T_A	-40	27	105	°C
MC9S12DT256M					
Operating Junction Temperature Range	T_J	-40	-	140	°C
Operating Ambient Temperature Range ²	T_A	-40	27	125	°C

NOTES:

1. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The absolute maximum ratings apply when this regulator is disabled and the device is powered from an external source.
2. Please refer to **Section A.1.8 Power Dissipation and Thermal Characteristics** for more details about the relation between ambient temperature T_A and device junction temperature T_J .

A.1.8 Power Dissipation and Thermal Characteristics

Power dissipation and thermal characteristics are closely related. The user must assure that the maximum operating junction temperature is not exceeded. The average chip-junction temperature (T_J) in °C can be obtained from:

A.2 ATD Characteristics

This section describes the characteristics of the analog to digital converter.

A.2.1 ATD Operating Characteristics

The **Table A-8** shows conditions under which the ATD operates.

The following constraints exist to obtain full-scale, full range results:

$V_{SSA} \leq V_{RL} \leq V_{IN} \leq V_{RH} \leq V_{DDA}$. This constraint exists since the sample buffer amplifier can not drive beyond the power supply levels that it ties to. If the input level goes outside of this range it will effectively be clipped.

Table A-8 ATD Operating Characteristics

Conditions are shown in Table A-4 unless otherwise noted							
Num	C	Rating	Symbol	Min	Typ	Max	Unit
1	D	Reference Potential Low High	V_{RL} V_{RH}	V_{SSA} $V_{DDA}/2$		$V_{DDA}/2$ V_{DDA}	V V
2	C	Differential Reference Voltage ¹	$V_{RH}-V_{RL}$	4.50	5.00	5.25	V
3	D	ATD Clock Frequency	f_{ATDCLK}	0.5		2.0	MHz
4	D	ATD 10-Bit Conversion Period Clock Cycles ² Conv, Time at 2.0MHz ATD Clock f_{ATDCLK}	N_{CONV10} T_{CONV10}	14 7		28 14	Cycles μs
5	D	ATD 8-Bit Conversion Period Clock Cycles ² Conv, Time at 2.0MHz ATD Clock f_{ATDCLK}	N_{CONV8} T_{CONV8}	12 6		26 13	Cycles μs
6	D	Recovery Time ($V_{DDA}=5.0$ Volts)	t_{REC}			20	μs
7	P	Reference Supply current 2 ATD blocks on	I_{REF}			0.750	mA
8	P	Reference Supply current 1 ATD block on	I_{REF}			0.375	mA

NOTES:

1. Full accuracy is not guaranteed when differential voltage is less than 4.50V
2. The minimum time assumes a final sample period of 2 ATD clocks cycles while the maximum time assumes a final sample period of 16 ATD clocks.

A.2.2 Factors influencing accuracy

Three factors - source resistance, source capacitance and current injection - have an influence on the accuracy of the ATD.

A.2.2.1 Source Resistance:

Due to the input pin leakage current as specified in **Table A-6** in conjunction with the source resistance there will be a voltage drop from the signal source to the ATD input. The maximum source resistance R_S

A.3.1.3 Sector Erase

Erasing a 512 byte Flash sector or a 4 byte EEPROM sector takes:

$$t_{\text{era}} \approx 4000 \cdot \frac{1}{f_{\text{NVMOP}}}$$

The setup time can be ignored for this operation.

A.3.1.4 Mass Erase

Erasing a NVM block takes:

$$t_{\text{mass}} \approx 20000 \cdot \frac{1}{f_{\text{NVMOP}}}$$

The setup time can be ignored for this operation.

A.3.1.5 Blank Check

The time it takes to perform a blank check on the Flash or EEPROM is dependant on the **location** of the first non-blank word starting at relative address zero. It takes one bus cycle per word to verify plus a setup of the command.

$$t_{\text{check}} \approx \text{location} \cdot t_{\text{cyc}} + 10 \cdot t_{\text{cyc}}$$

Table A-11 NVM Timing Characteristics

Conditions are shown in Table A-4 unless otherwise noted							
Num	C	Rating	Symbol	Min	Typ	Max	Unit
1	D	External Oscillator Clock (MC9S12DT256C< V, M)	f_{NVMOSC}	0.5		50 ¹	MHz
2	D	Bus frequency for Programming or Erase Operations	f_{NVMBUS}	1			MHz
3	D	Operating Frequency	f_{NVMOP}	150		200	kHz
4	P	Single Word Programming Time	t_{swpgm}	46 ²		74.5 ³	μs
5	D	Flash Burst Programming consecutive word ⁴	t_{bwpgm}	20.4 ²		31 ³	μs
6	D	Flash Burst Programming Time for 32 Words ⁴	t_{brpgm}	678.4 ²		1035.5 ³	μs
7	P	Sector Erase Time	t_{era}	20 ⁵		26.7 ³	ms
8	P	Mass Erase Time	t_{mass}	100 ⁵		133 ³	ms
9	D	Blank Check Time Flash per block	t_{check}	11 ⁶		32778 ⁷	t_{cyc}
10	D	Blank Check Time EEPROM per block	t_{check}	11 ⁶		2058 ⁷	t_{cyc}

NOTES:

1. Restrictions for oscillator in crystal mode apply!
2. Minimum Programming times are achieved under maximum NVM operating frequency f_{NVMOP} and maximum bus frequency f_{bus} .

A.5.1.5 Pseudo Stop and Wait Recovery

The recovery from Pseudo STOP and Wait are essentially the same since the oscillator was not stopped in both modes. The controller can be woken up by internal or external interrupts. After t_{WTS} the CPU starts fetching the interrupt vector.

A.5.2 Oscillator

The device features an internal Colpitts and Pierce oscillator. The selection of Colpitts oscillator or Pierce oscillator/external clock depends on the $\overline{XCLKS}$ signal which is sampled during reset. By asserting the $\overline{XCLKS}$ input during reset this oscillator can be bypassed allowing the input of a square wave. Before asserting the oscillator to the internal system clocks the quality of the oscillation is checked for each start from either power-on, STOP or oscillator fail. t_{CQOUT} specifies the maximum time before switching to the internal self clock mode after POR or STOP if a proper oscillation is not detected. The quality check also determines the minimum oscillator start-up time t_{UPOSC} . The device also features a clock monitor. A Clock Monitor Failure is asserted if the frequency of the incoming clock signal is below the Assert Frequency f_{CMFA} .

Table A-15 Oscillator Characteristics

Conditions are shown in Table A-4 unless otherwise noted							
Num	C	Rating	Symbol	Min	Typ	Max	Unit
1a	C	Crystal oscillator range (Colpitts)	f_{OSC}	0.5		16	MHz
1b	C	Crystal oscillator range (Pierce) ¹⁽⁴⁾	f_{OSC}	0.5		40	MHz
2	P	Startup Current	i_{OSC}	100			μA
3	C	Oscillator start-up time (Colpitts)	t_{UPOSC}		8^2	100^3	ms
4	D	Clock Quality check time-out	t_{CQOUT}	0.45		2.5	s
5	P	Clock Monitor Failure Assert Frequency	f_{CMFA}	50	100	200	KHz
6	P	External square wave input frequency ⁴	f_{EXT}	0.5		50	MHz
7	D	External square wave pulse width low	t_{EXTL}	9.5			ns
8	D	External square wave pulse width high	t_{EXTH}	9.5			ns
9	D	External square wave rise time	t_{EXTR}			1	ns
10	D	External square wave fall time	t_{EXTF}			1	ns
11	D	Input Capacitance (EXTAL, XTAL pins)	C_{IN}		7		pF
12	C	DC Operating Bias in Colpitts Configuration on EXTAL Pin	V_{DCBIAS}		1.1		V

NOTES:

1. Depending on the crystal a damping series resistor might be necessary
2. $f_{osc} = 4\text{MHz}$, $C = 22\text{pF}$.
3. Maximum value is for extreme cases using high Q, low frequency crystals
4. $\overline{XCLKS} = 0$ during reset